

## Surface Mount Fast Recovery Rectifiers

### FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



**DO-214AC (SMA)**

### MECHANICAL DATA

**Case:** DO-214AC (SMA)

Molding compound, UL flammability classification rating 94V-0

Base P/N with suffix "G" on packing code - Green compound (halogen-free)

Base P/N with prefix "H" on packing code - AEC-Q101 qualified

**Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test

with prefix "H" on packing code meet JESD 201 class 2 whisker test

**Polarity:** Indicated by cathode band

**Weight:** 0.06 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T <sub>A</sub> =25°C unless otherwise noted)									
PARAMETER	SYMBOL	RS 2AA	RS 2BA	RS 2DA	RS 2GA	RS 2JA	RS 2KA	RS 2MA	UNIT
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I <sub>F(AV)</sub>	1.5							A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50							A
Maximum instantaneous forward voltage (Note 1) @ 1.5 A	V <sub>F</sub>	1.3							V
Maximum reverse current @ rated VR T <sub>J</sub> =25 °C T <sub>J</sub> =125 °C	I <sub>R</sub>	5 200							μA
Maximum reverse recovery time (Note 2)	T <sub>rr</sub>	150			250		500		ns
Typical junction capacitance (Note 3)	C <sub>j</sub>	50							pF
Typical thermal resistance	R <sub>θJL</sub> R <sub>θJA</sub>	18 55							°C/W
Operating junction temperature range	T <sub>J</sub>	- 55 to +150							°C
Storage temperature range	T <sub>STG</sub>	- 55 to +150							°C

Note 1: Pulse test with PW=300μs, 1% duty cycle

Note 2: Reverse Recovery Test Conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

ORDERING INFORMATION					
PART NO.	AEC-Q101 QUALIFIED	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING
RS2xA (Note 1)	Prefix "H"	R3	Suffix "G"	SMA	1,800 / 7" Plastic reel
		R2		SMA	7,500 / 13" Paper reel
		M2		SMA	7,500 / 13" Plastic reel
		F3		Folded SMA	1,800 / 7" Plastic reel
		F2		Folded SMA	7,500 / 13" Paper reel
		F4		Folded SMA	7,500 / 13" Plastic reel
		N/A		E3	Clip SMA
	E2			Clip SMA	7,500 / 13" Plastic reel

Note 1: "x" defines voltage from 50V (RS2AA) to 1000V (RS2MA)

EXAMPLE					
PREFERRED P/N	PART NO.	AEC-Q101 QUALIFIED	PACKING CODE	GREEN COMPOUND CODE	DESCRIPTION
RS2MA R3	RS2MA		R3		
RS2MA R3G	RS2MA		R3	G	Green compound
RS2MAHR3	RS2MA	H	R3		AEC-Q101 qualified

**RATINGS AND CHARACTERISTICS CURVES**

(TA=25°C unless otherwise noted)

FIG. 1 FORWARD CURRENT DERATING CURVE

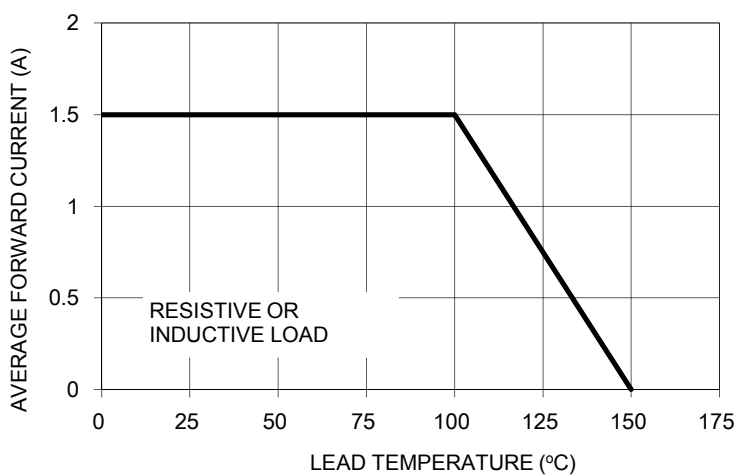


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

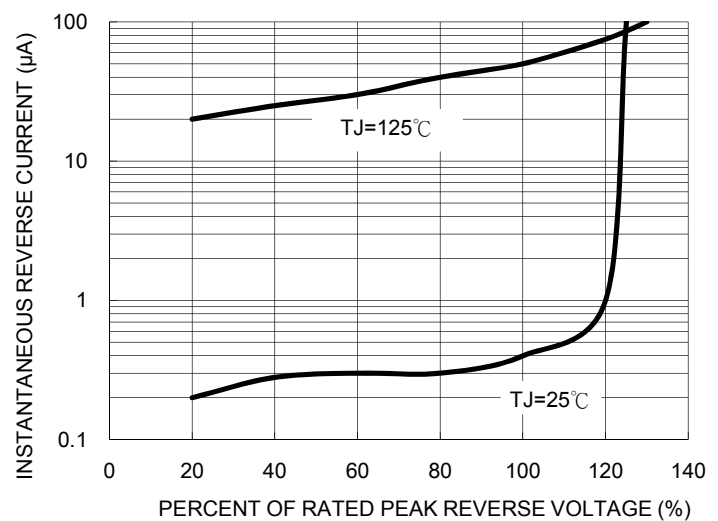


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

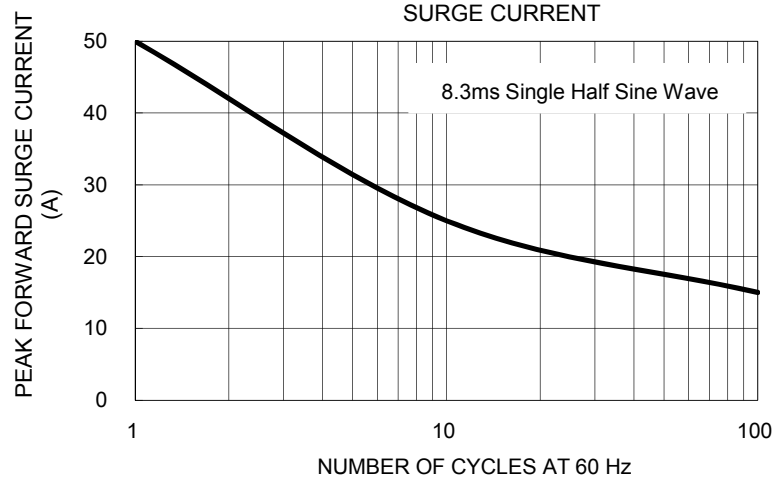


FIG. 4 TYPICAL FORWARD CHARACTERISTICS

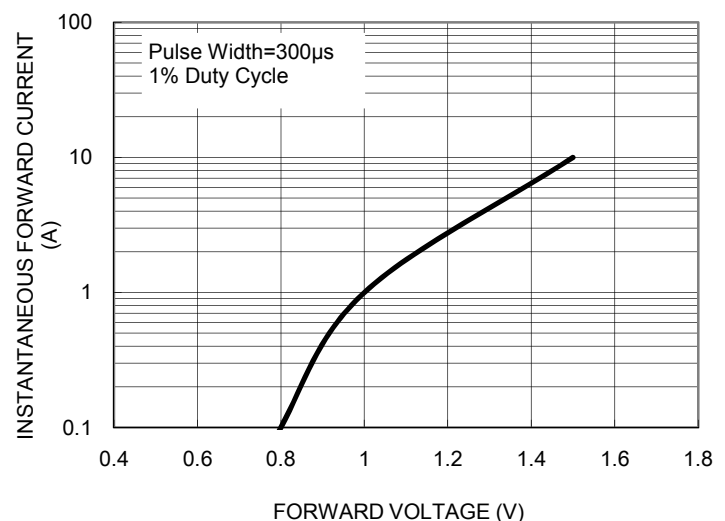


FIG. 5 TYPICAL JUNCTION CAPACITANCE

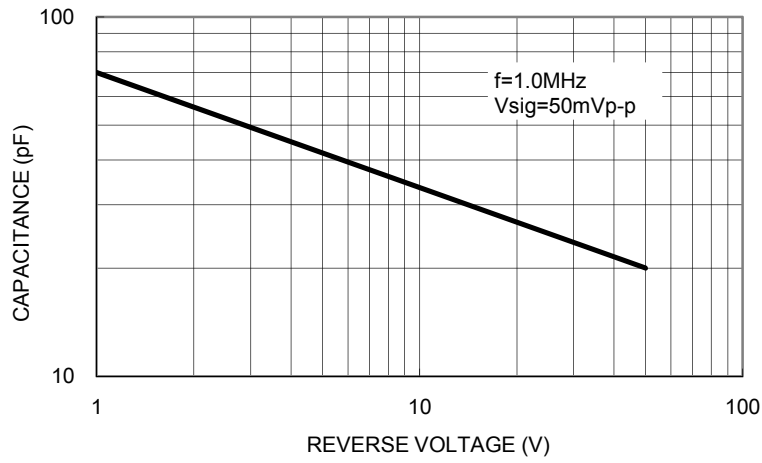
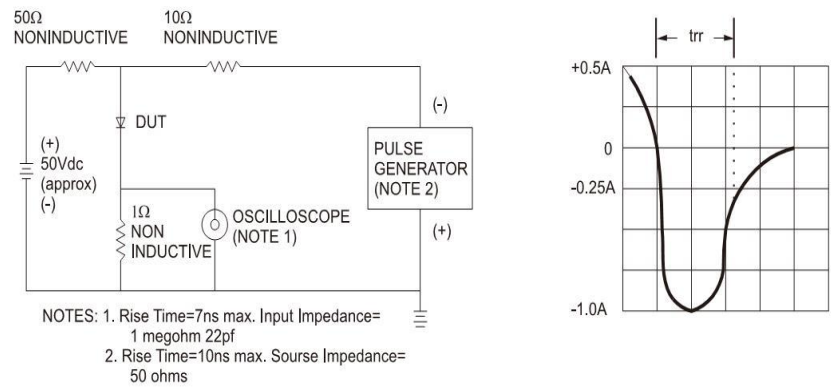
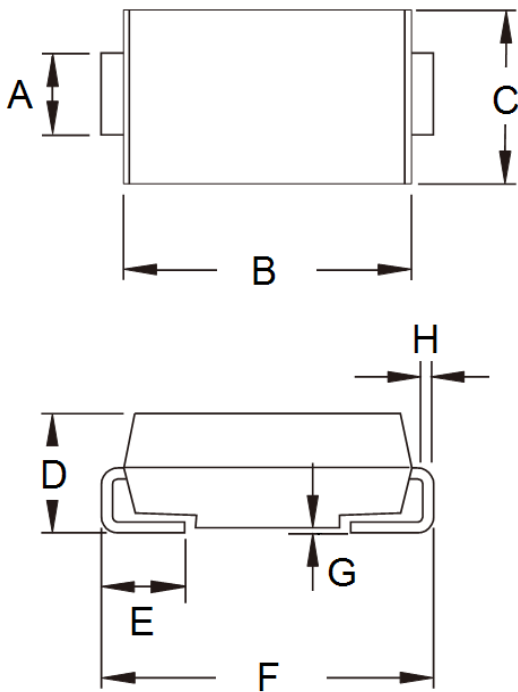


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

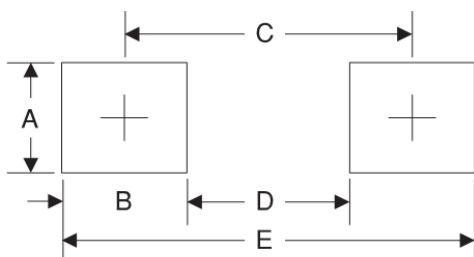


PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
B	4.06	4.60	0.160	0.181
C	2.29	2.83	0.090	0.111
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.056
F	4.95	5.33	0.195	0.210
G	0.10	0.20	0.004	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



- P/N = Specific Device Code
- G = Green Compound
- YW = Date Code
- F = Factory Code